

DESIGNCORE™

D3CM-IMX224 CAMERA MODULE



Enclosed Camera Module enables evaluation of imaging platforms designed with production in mind.

Enclosed Camera Module for Embedded Vision System Evaluation and Demonstration

This Camera Module is ideal for vision system evaluation and demo platforms. It is designed for use with D3 Engineering's DesignCore™ RVP (Rugged Vision Platform) Development Kits. The D3CM features the Sony IMX224 sensor and optics in an unsealed (non-rugged) enclosure. It has industrial environmental ratings.

This D3CM Camera Module features a SerDes camera interface (FPD-Link III) and offers higher performance than COTS camera modules.

After evaluation, D3 Engineering can customize Camera Modules to your OEM/ODM requirements. We develop custom ISP and software drivers, add local power or autofocus, design to your environmental specifications or standards, and more. We support your product with advanced manufacturing in the USA or offshore, in volumes from 10 to 10 million.

FEATURES

Sony IMX224 Image Sensor

FPD-Link III Serializer

Resolution: 1280x960 (Quad VGA)

Frame Rate: 60fps Default (120fps Max)

MIPI-CSI2 Over FPD-Link III (Serial) Video Output

Back-Channel Configuration Connectivity

APPLICATIONS

Automotive Advanced Driver Assist (ADAS) Systems

Front or rear camera

3D Surround View

Driver monitoring

Camera monitoring systems (CMS)

Autonomous Trucking / Transportation Systems

Autonomous Guided Vehicles (AGV)

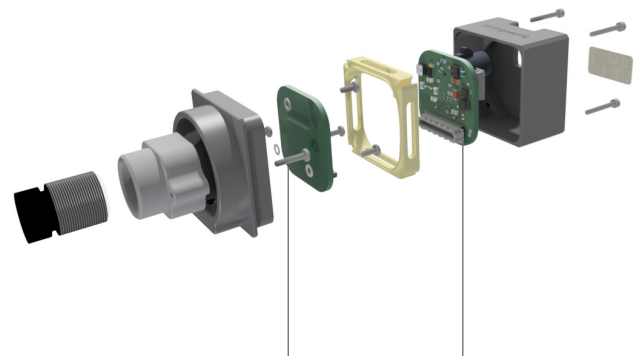
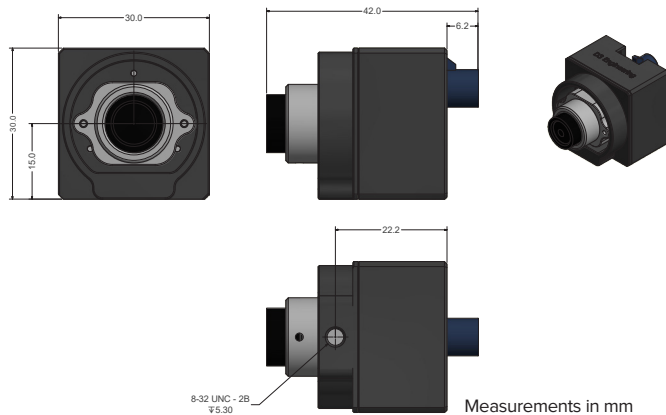
Collaborative Robotics

360-Degree Vision Systems

SPECIFICATIONS

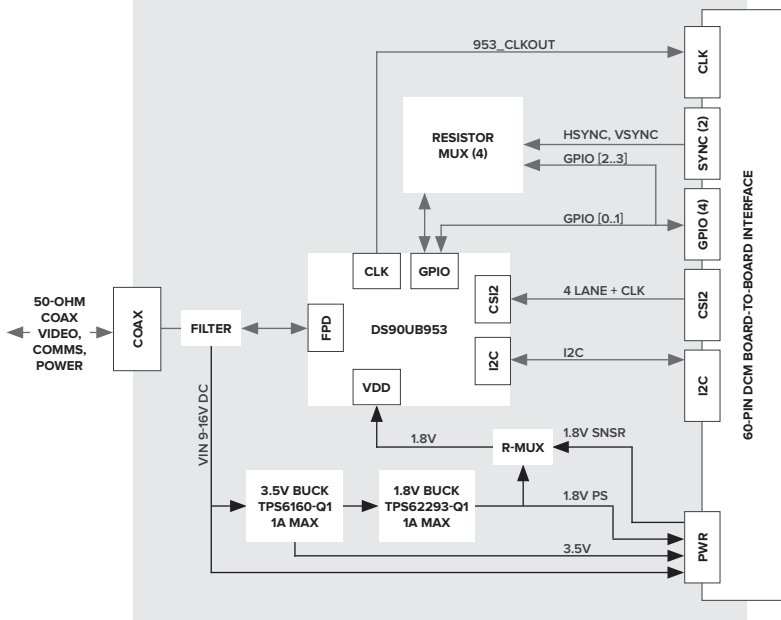
Sensor	Sony IMX224
Megapixels	2.07
Video Resolution	1280x960 (Quad VGA)
Frame Rate	60fps default (120fps max)
Sensor Size	6.09mm (type 1/3)
Lens Options	Interchangeable M12 lens Default: 76 HfVf1.7 Sunex DSL958G lens Multiple IR cut filter options
Image Format Packing	10/12 bit Raw Bayer, linear and HDR modes
Voltage Input	9-16V, 12V nominal
Video Output	MIPI-CSI2 over FPD-Link III (serial)
Dimensions	L:42 W:30 H:30 (mm)
Mounting Options	8/32 mounting hole
Temperature Range	-40C to 105C
Enclosure Type	DCM enclosure
Communication	I2C Address Image Sensor 0x1A I2C Address Serializer 0x2C

DesignCore™ Platform Supported:
RVP-TDA3x Development Kit
(4GHz FPD-Link)

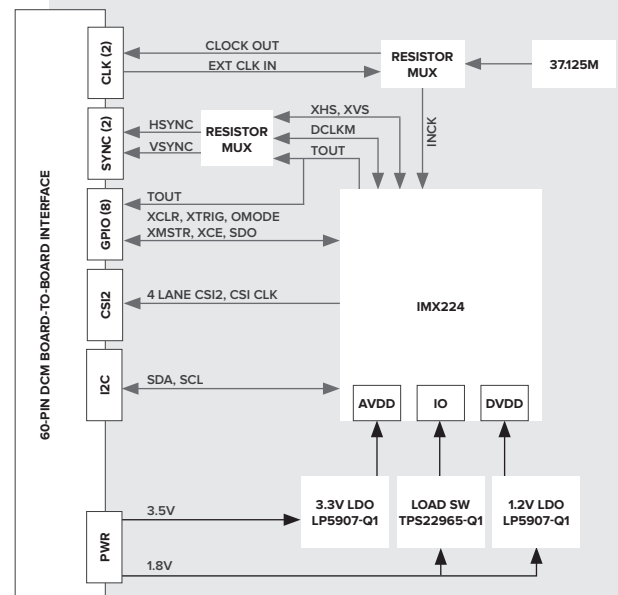


IMX224 Image Sensor Board DS90UB953 FPD-Link III Interface Board

DS90UB953 FPD-LINK III INTERFACE BOARD



IMX224 IMAGE SENSOR BOARD



CABLE ORDERING INFORMATION

D3CM products are not supplied with cables. D3 tests all D3CM products with Pasternack PE38754Z series cables. Contact D3 for more information on cables and accessories.

ACCELERATE TIME TO MARKET

D3 Engineering speeds embedded system development with our proven DesignCore™ Camera Modules and full-cycle embedded product development services. Our expertise in imaging system design will help you get to market faster, while reducing the risks and costs of new product development.

CALL: 1-585-429-1550

EMAIL: sales@D3Engineering.com

VISIT: D3Engineering.com/Solutions/Embedded-Vision